



## Material Content Data Sheet



Halogen-Free

**Sales Product Name** TLE9274QX V33

**Issued**

08. February 2022

**MA#** MA005562343

**Package** PG-VQFN-48-31

**Weight\***

129.75 mg

Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	3.989	3.07	3.07	30743	30743
leadframe	inorganic material	phosphorus	7723-14-0	0.018	0.01		138	
	non noble metal	zinc	7440-66-6	0.072	0.06		552	
	non noble metal	iron	7439-89-6	1.433	1.10		11046	
	non noble metal	copper	7440-50-8	58.193	44.85	46.02	448493	460229
wire	non noble metal	copper	7440-50-8	0.580	0.45	0.45	4473	4473
encapsulation	organic material	carbon black	1333-86-4	0.184	0.14		1415	
	plastics	epoxy resin	-	7.771	5.99		59888	
	inorganic material	silicondioxide	60676-86-0	53.232	41.03	47.16	410260	471563
leadfinish	non noble metal	tin	7440-31-5	2.596	2.00	2.00	20010	20010
plating	noble metal	silver	7440-22-4	0.614	0.47	0.47	4731	4731
glue	plastics	epoxy resin	-	0.246	0.19		1898	
	noble metal	silver	7440-22-4	0.824	0.64	0.83	6353	8251
*deviation	< 10%	Sum in total:				100.00		1000000

### Important Remarks:

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